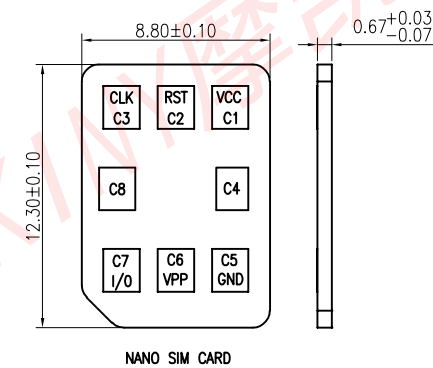
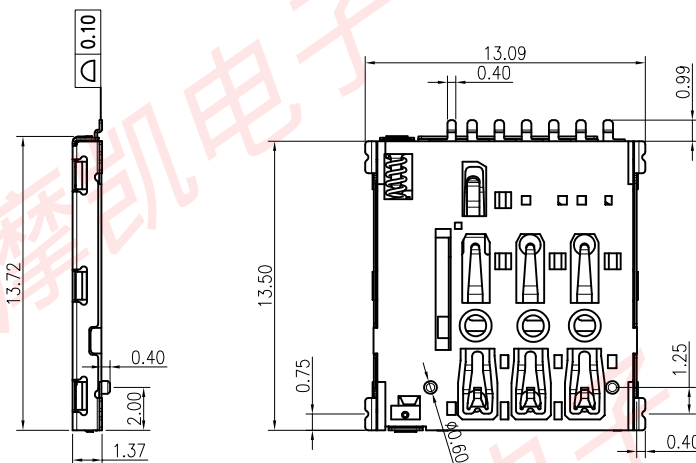
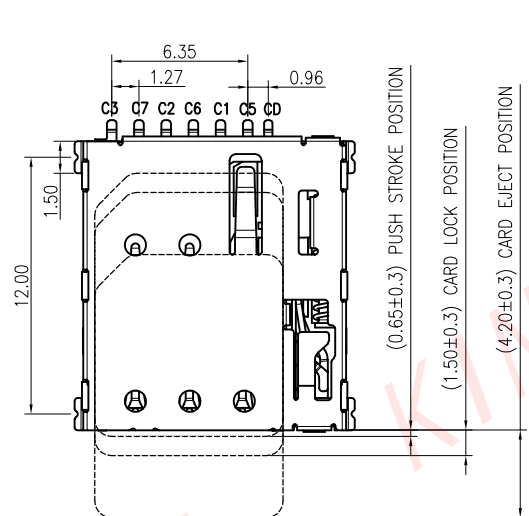
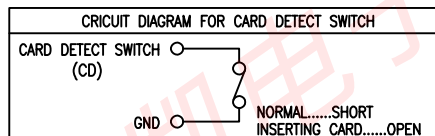
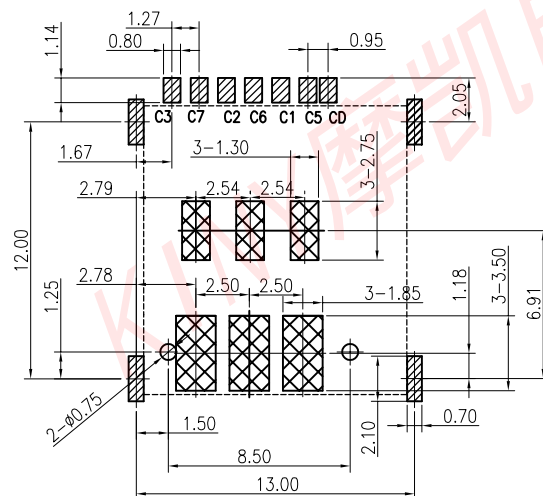
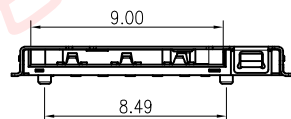


* 所有原料材质, 生产制程, 电镀必须符合HF要求



NOTES:

- MATERIAL:
HOUSING: HI-TEMP. PLASIC UL 94V-0
CONTACT: COPPER ALLOY
SHELL: STAINLESS STEEL
- PLATING :
TERMINAL:
CONTACT AREA: Au GOLD FLASH.
SOLDER AREA: AU GOLD FLASH.
UNDER PLATE: NICKEL.
SHELL: NICKEL PLATED OVER ALL.
SOLDER AREA: GOLD FLASH.
- SPECIALITY:
3.1 Rated current: 1.0A
3.2 Rated voltage: 30V
3.3 Contact Resistance: 100mΩ MAX
3.4 Insulation Resistance: 1000MΩ MIN 500V DC
3.5 Dielectric withstanding voltage: 500V AC.
3.6 Solder ability: 260±0/-5°C, 30±10s.
3.7 Durability: 5000 Cycles Min.
3.8 Operating condition: Temperature -40°C~+85°C;
Humidity 80% R.H MAX



RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

PAD
 KEEP OUT AREA

KINY

东莞市摩凯电子有限公司

DIMENSIONS INIT: mm
UNLESS OTHERWISE SPECIFIABLE
DIMENSION TOLERANCE
X.X: ± 0.35
X.XX: ± 0.25
X.XXX: ± 0.10
ANGULAR: ± 2°

PRODUCT NAME : NANO SIM P-P H1.37	DRAWING: Aaron	DATE: 2020.09.17
PRODUCT NO. : NS137-T1131-01-W	CHECK: Alex	DATE: 2020.09.17
DRAWING NO. : D-NS137-T1131-01-W	APPROVED: Alex	DATE: 2020.09.17
SCALE: 1:1	DWG ID: C D	REV.: A
		PAGE: 1 of 1

A	----	NEW RELEASE	Aaron	2020.09.17
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
1		2	3	4